

# NTE424 Non-Silicone Heat Sink Compound 1 oz. Plunger Tube

## **Description:**

NTE424 heat sink compound is a grease-like, non-silicone, non-migrating material heavily impregnated with heat-conductive metal oxides. This formulation provides high thermal conductivity, low bleed and high temperature stability.

NTE424 has been engineered to solve the problems of contamination and migration associated with silicone-based products. A unique poly synthetic-based thermal grease used to insure quick, efficient heat transfer and dissipation for the full operational life of your hardware.

## **Key Features and Benefits:**

- Non-Silicone Advantages/No Creep or Migration over Wide Temperature Range
- Low Interface Thermal Resistance (0.03°C–In²/W)
- High Thermal Conductivity, High Dielectric Strength
- Exceptionally Low Bleed and Evaporation
- Will Not harden, Dry-Out or Melt
- Will Not Contaminate Solder bath or Other Devices
- Non-Toxic
- Reworkable/Easy to Remove
- Easy to Dispense

#### **Common Uses:**

- CPUs
- LED
- IGBT Modules
- Power Rectifiers

#### **Typical Properties:**

Viscosity	. Thixotropic Paste
Specific Gravity @ +25°C	2.7
Color	White
Evaporation @ +200°C, 24 Hours, %/Wt	0.3
Thermal Conductivity, (ASTM D5470)	
Cal/Sec. Cm. °C	23 x 10 <sup>-4</sup>
BTÚ.ln/(Hr.Ft <sup>2</sup> .°F)	6.9
Thermal Resistance (°C-In²/W)	0.03
Electrical Properties:	
Dielectric Strength (ASTM D150) 0.05" gap, V/mil	350
Dielectric Constant (ASTM D150) +25°C @ 1000Hz	
Dissipation Factor (ASTM D150) +25°C @ 1000Hz	
Volume Resistivity (ASTM D257) Ohm-cm	
Operating Temperature Range	
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**Typical Applications:** 

The NTE424 heat sink compound is applied to the base and mounting studs of transistors, diodes and silicon controlled rectifiers (SCRs). In these situations, a small amount of the thermal grease is applied using either the dispensing of screen printing/stencil methods. NTE424 can be used as a high-voltage corona suppressant/non-flammable coating, in connections for flyback transformers located in TV sets and similar design applications. It is also used in mounting semiconductor devices; thermoelectric modules; power transistors and diodes; coupling entire heat generating assemblies to chassis; heat transfer medium on ballasts; thermal joints; thermocouple wells; mounting power resistors; and for any devices where efficient cooling is required in major industries including: electronic (computer, appliance, wireless, etc.), automotive and electrical.

#### Shelf-Life:

The NTE424 has a shelf-life of 5 years at room temperature (+25°C) in unopened containers. Slight settling of the filler may occur during long-term storage. In this case, it is recommended to re-disperse the filler by hand or mechanical mixing. Refrigerate material at 0° to +10°C to avoid any settling.

### Clean-Up:

Standard approved clean-up and disposal procedures should be followed in every situation. The use of disposable containers and utensils are recommended whenever possible to simplify and expedite clean-up. However, when disposable containers are impractical, NTE424 can be removed by cleaning solvents such as Mineral Spirit (Paint Thinner), Heptane or Isopropyl Alcohol.